

## Standard Assembly Build Sheet (Air Cavity Package - OmPP, OCPP, Ceramic, etc.)

Original request  
Changed request

Rev # \_\_\_\_\_

QP Internal S.O. #: \_\_\_\_\_

QP Quote #: \_\_\_\_\_

QP Sales Contact: \_\_\_\_\_

### CUSTOMER CONTACT INFORMATION

Company: \_\_\_\_\_

Contact Name: \_\_\_\_\_ Date: \_\_\_\_\_

Phone: \_\_\_\_\_

Email: \_\_\_\_\_

P.O. #: \_\_\_\_\_

**Is this item under the jurisdiction of the International Traffic in Arms Regulations (ITAR)?** Yes No

### DELIVERY REQUEST

LEAD TIMES WILL VARY BASED ON SCOPE OF WORK AND QUANTITY. EXPEDITE (1-2 DAYS). PREMIUM(8 HRS).

Standard

Expedite

Premium

### DIE INFORMATION:

ALL WAFER PROCESSING REQUIRES A BACKGRIND/DICING BUILD SHEET TO BE COMPLETED AND ATTACHED SEPARATELY.

Die Format: Waffle Pack Gel-Pak Diced Wafer on Tape Wafer (requires processing) Other: \_\_\_\_\_

Die Size: \_\_\_\_\_ X \_\_\_\_\_  $\mu$ m or mils

**(a) Wafer ID/Die ID:**

**(b) Lot #**

**(c) Qty of Devices to be Assembled Per ID**

Pad Pitch: \_\_\_\_\_ X \_\_\_\_\_  $\mu$ m or mils

1a. \_\_\_\_\_

1b. \_\_\_\_\_

1c. \_\_\_\_\_

Pad Dims: \_\_\_\_\_ X \_\_\_\_\_  $\mu$ m or mils

2a. \_\_\_\_\_

2b. \_\_\_\_\_

2c. \_\_\_\_\_

Pad Opening: \_\_\_\_\_ X \_\_\_\_\_  $\mu$ m or mils

3a. \_\_\_\_\_

3b. \_\_\_\_\_

3c. \_\_\_\_\_

Thickness: \_\_\_\_\_  $\mu$ m or mils

4a. \_\_\_\_\_

4b. \_\_\_\_\_

4c. \_\_\_\_\_

Probed?

Passivated?

### DEVICE INFORMATION

Device Name: \_\_\_\_\_ Pin Count: \_\_\_\_\_ Lead Pitch: \_\_\_\_\_ Die Per Package: \_\_\_\_\_ Wire Count Per Package: \_\_\_\_\_

Qty of Devices to be Assembled: \_\_\_\_\_ Body Size (mm): \_\_\_\_\_ X \_\_\_\_\_

Packages provided by: Customer QP Technologies Packages Require Plastic Decapsulation?

Package Type OmPP Ceramic Other \_\_\_\_\_

Package Description: \_\_\_\_\_

### SPECIAL INSTRUCTIONS (ATTACH ADDITIONAL DOCUMENTS IF NEEDED)

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### CUSTOMER FURNISHED MATERIALS:

PLEASE LIST ANY ADDITIONAL CFM THAT WILL BE SHIPPED TO QP. IF MORE SPACE IS NEEDED, ATTACH ADDITIONAL DOCUMENTS.

- |          |          |          |
|----------|----------|----------|
| 1. _____ | 2. _____ | 3. _____ |
| 4. _____ | 5. _____ | 6. _____ |
| 7. _____ | 8. _____ | 9. _____ |

## ASSEMBLY FLOW

ALL WIRE BONDING REQUIRES A VISUAL BONDING DIAGRAM TO BE ATTACHED WITH CLEARLY LABELED PIN 1, DIE ORIENTATION.

Select Die From:      Center of Wafer(s)      Wafer Map(s)      Reticle Map (include with Build Sheet)

\*STANDARD MATERIAL. OTHER OPTIONS MAY INCREASE COST/LEADTIME.

Die Attach Material: \_\_\_\_\_ Conductive Epoxy\*      \_\_\_\_\_ Thermally Conductive/Electrically Conductive Material  
                                 \_\_\_\_\_ Non-Conductive Epoxy\*

Gold Wire Diameter:      \_\_\_\_\_ 0.7 mil      \_\_\_\_\_ 0.8 mil      \_\_\_\_\_ 1.0 mil\*      \_\_\_\_\_ 1.2 mil  
                                 \_\_\_\_\_ 1.3 mil      \_\_\_\_\_ 1.5 mil      \_\_\_\_\_ 2.0 mil

Die to Die Bond      Lead to Down Bond (or jumper wire)      Lead to Lead Bond  
Gold Ribbon:    Yes      No  
Aluminium Wire: Heavy      Fine

**Please make a selection from Group A OR a selection from Group B AND Group C**

### GROUP A (Encapsulation)

\_\_\_\_\_ Glop Top  
\_\_\_\_\_ Remolded/Flattened  
\_\_\_\_\_ Dam & Fill  
\_\_\_\_\_ Other(May increase turn time and cost) \_\_\_\_\_ Other(May increase turn time and cost)  
\_\_\_\_\_

### GROUP B (Lid Type)

\_\_\_\_\_ Ceramic  
\_\_\_\_\_ Plastic  
\_\_\_\_\_ Glass  
\_\_\_\_\_ Other(May increase turn time and cost)

### GROUP C (Lid Sealing)

\_\_\_\_\_ Epoxy Seal  
\_\_\_\_\_ Epoxy on Two Corners  
\_\_\_\_\_ Epoxy on Four Corners  
\_\_\_\_\_ Solder Seal  
Other(May increase turn time and cost)

**Marking** (MAX CHARACTER LENGTH AND NUMBER OF ROWS WILL VARY BASED ON PACKAGE SIZE. CONTACT QP FOR DESIGN APPROVAL AND COSTS.) :

Mark pin 1 on device?

No Marking

Hand Mark (Max. 1-3 characters): \_\_\_\_\_

Pad Print (White ink) - E-mail artwork in native .EPS or .AI file format

Laser Mark - E-mail artwork in native .EPS or .AI file format

Serialization (MAY INCREASE MARKING COSTS/LEADTIME). Please describe:

\_\_\_\_\_  
\_\_\_\_\_



Please mark pin 1 corner and indicate how marking should appear on package relative to pin 1.

Lead Trim?    Yes      No      Requested Lead Length: \_\_\_\_\_ mil    (If yes, please include a package outline drawing)

## SHIPPING (Contact QP with any special requests)

Reject Parts Disposition:    Return to Customer    Bag and Tag    Destroy

**\*Unless otherwise noted all extra materials will be returned.**

Shipping Method (Please Select)

Account #: \_\_\_\_\_

Pickup      FedEx      DHL      UPS      Courier      Special Instructions

Ship To Address (Finished Product):

Attn: \_\_\_\_\_

Address: \_\_\_\_\_

Ship To Address (Excess Materials):

Attn: \_\_\_\_\_

Address: \_\_\_\_\_

Additional Shipping Instructions (Including Email For Shipping Notices):